

JSO53 Series Material Declaration

Total Weight: 33,4 mg
Size: 5.0 x 3.2 x 0.75 mm



RoHS (2011/65/EC) compliant



Part	Weight of parts (mg)	Content substance	CAS No	Content (mg)	Content (wt%)	
Leadframe	12.582	C194 Alloy	Copper	7440-50-8	12.270	36.70
			Iron	7439-89-6	0.297	0.89
			Zinc	7440-66-6	0.015	0.04
Plating	0.006	NiPdAu	Nickel	7440-02-0	0.006	0.02
			Palladium	7440-05-3	<0.001	Trace
			Gold	7440-57-5	<0.001	Trace
Die 1	0.5	CEMOS Die	Si	7440-21-3	0.500	1.50
Die 2	0.04	MEMS Die	Si	7440-21-3	0.040	0.12
Die attach material 1	0.256	Non-Conductive epoxy	Epoxy Resin	Proprietary	0.180	0.54
			Glycol Ether	25068-38-6	0.038	0.11
			Fused Silica	60676-86-0	0.020	0.06
			Additive	Proprietary	0.018	0.05
Die attach material 2	0.022	Conductive epoxy	Silver	7440-22-4	0.017	0.05
			Acrylate	Proprietary	0.004	0.01
			Resin	Proprietary	0.001	Trace
			Additive	Proprietary	<0.001	Trace
Wire	0.108	Gold	Au	7440-57-5	0.108	0.32
Encapsulation	19.919	Epoxy Resin	Fused silica	60676-86-0	18.027	53.93
			Epoxy resin	Proprietary	0.936	2.80
			Phenol resin	Proprietary	0.936	2.80
			Carbon black	1333-86-4	0.020	0.06